

TECHNICAL DATA SHEET

Drei Bond 1385

Revision: 04.10.2018
Version: 1.005



PRODUCT PROPERTIES

DB 1385 adhesive is a single-component anaerobic adhesive with high strength class, designed for securing, sealing and fastening threaded connections and form-fit connections. It offers high technical parameters when bonding passive materials. In its cured state, this product exhibits high resistance to dynamic and thermal loads. It can also be applied to slightly oiled surfaces.

PHYSICAL PROPERTIES

Appearance	liquid
Colour	green
Odor	methacrylate
Specific weight	1.05 g/ml
Viscosity at 25 °C	400 – 600 mPa·s Brookfield
Gap filling	M20 - 0,15 mm
Temperature range	-55°C/+175°C

CURING PROPERTIES

Bold M 10 x 20 Zn – quality 8.8 – nut h = 0.8 d at +25°C:

Handling cure time	1 – 18 min
Functional cure time	1 – 3 h
Full cure time	2 – 4 h

Curing rate depends on the gap, assembly clearance, material surfaces and temperature. The use of Drei Bond activator speeds up the curing process.

PROPERTIES IN THE CURED STATE

Shear strength (ISO 10123)	25 – 30 N/mm ²
Locking torque (ISO 10964)	
Breakaway:	25 – 35 Nm
Prevailing	50 – 70 Nm
Impact strength (ASTM D950)	5 – 12 kJ/m ²

CHEMICAL RESISTANCE

According to the document “Resistance of Drei Bond anaerobic products to liquids, gases and solids”.

STORAGE

- 12 months at RT in unopened packaging.

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PACKAGE UNITS

- For manual application 10 ml, 50 ml, 250 ml
- For industrial use 1 l, 2 l

DIRECTIONS FOR USE

- Contaminated surfaces should be mechanically cleaned and degreased using Drei Bond Cleaner 3200. The prepared surfaces should be dry.
- Apply a small amount of the adhesive to the thread surface at the joint.

When sealing threaded connections, apply the adhesive to the first three turns of the external thread, evenly over the entire circumference.

- When bonding blind threads, cover the internal thread.
- For form-fit connections, assemble with a rotating motion.
- For press-fit connections, apply the adhesive to both surfaces.
- After 1 minute, do not move the bonded components, as this may break the bonds being formed.
- Increased temperature and the use of an activator accelerate the curing process.
- Heating the bond above +100°C facilitates disassembly and removal of old adhesive residue.

Drei Bond 5930 or 5900 activator should be used in the following cases:

- bonding components at temperatures below +15°C,
- bonding passive components,
- when it is necessary to shorten the technical assembly time.

For automatic processing we recommend to use Drei Bond application systems from stand-by equipments to full automatic CNC-controlled dosing machines.

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